

AMENDMENTS TO THE SPECIFICATION

IN THE SPECIFICATION:

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Please amend the paragraph beginning at line 2, through line 22, with the following:

As a process for preparing these electromagnetic wave shielding materials, it has generally been employed a method in which a conductive metal such as silver, copper, nickel, indium, etc., or a conductive metal compound of these metals is formed on a transparent resin film substrate as a metal thin film by a sputtering method, an ion plating method, an ion beam assist method, a vacuum deposition method, or a wet coating method. However, when a film thickness or pattern fine line width is set with a degree that the transparency can be maintained, a surface resistance of the conductive layer becomes ~~too large to cause too small shielding effect~~ so large to cause as to cause small shielding effect, so that there is a problem that, for example, it is difficult to obtain a shielding effect of 30 dB or higher over higher frequency bands of 300 MHz or higher. Accordingly, an electromagnetic wave shielding material having high transparency and excellent in shielding property over higher frequency band region has been desired. Also, in recent years, demands of the electromagnetic wave shielding material are expanded, and a preparation process that is low cost and has high productivity has been desired.

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Please amend the paragraph beginning at line 32, through line 35, with the following:

Also, ~~for the purpose of heightening a property capable of admitting with eyes~~ for the purpose of making it easier to see a scene through the fine line pattern(s), it is preferred to subject the surface of the plating layer to a blackening treatment by using an acid or an alkali, or by plating.